Design Rules

RIGID.flex 1F-xRi

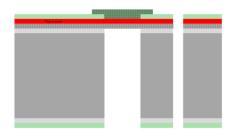


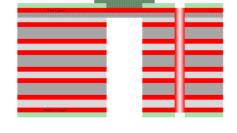
These design rules apply to:

RIGID.flex PCBs with one copper layer on flexible polyimide material, externally located.

Application in accordance with IPC 2223 Use A: Flex-to-install, UL marking according UL94 and UL796F possible.

Examples:





1F-0Ri: 1 copper layer

1F-7Ri: 8 copper layers with PTH

Nomenclature: Ri = Rigid, F = Flex

Basic instructions

- Please comply with general standards, such as IPC or IEC
- Please refer to the valuable hints and tips in our RIGID.flex Design Guide at www.we-online.com/flex.
- Please refer to our BASIC Design Rules for rules on conductor widths, spacings, via and pad sizes as well as solder mask at www.we-online.com/basic.
- Filling of PTHs (plated through holes):
 - Do not use open holes in solder pads! Keep at least 400µm distance from solder pads to holes to be plugged on both sides (Via plugging, IPC-4761 type III). For vias according to IPC-4761 type VII (filled and capped) please consult us for allowed design rules (conductor spacing)!
- Lift-off areas <u>attention</u>: NO copper layout below the flex and NO vias permitted in these areas!
- Flexible and rigid-flexible circuit boards must be dried before they are assembled. Further information about this is available at www.we-online.com/dryingprocess.
- Copper removal is required in ground or reference layers for drying.
 - o Recommendation: Copper openings 0.3mm per 1mm length of copper.
- Flex-to-install bending radius: Installation Use A in accordance with IPC-2223 up to 90° bending angle:



- 1 copper layer: 10 x total thickness (IPC-2223 section 5.2.3.3)
- For use in more demanding conditions, please contact us.
- We will be happy to create the optimal delivery panel for you (best price!).

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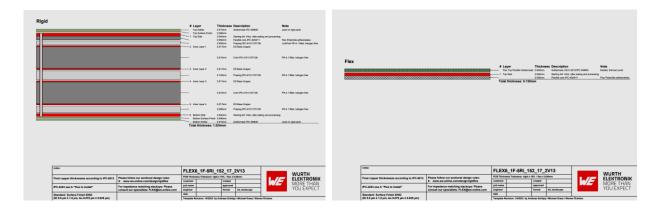


Material specifications

Material	Standard	Spec.	Description	Application	
		sheet			
Flexible base	IPC-4202	11	Polyimide adhesive less	Standard	
material	IPC-4202	2	Polyimide with glue	Not recommended for	
				microvia and hand-soldering	
	JPCA-BM03				
Rigid material	IPC-4101	128	FR4.1 Tg 150°C, filled;	Standard for RIGID.flex	
(cores, prepregs)			low-halogen, low CTE(z)		
LowFlow Prepreg	IPC-4101	128	FR4.1 Tg 150°C	Standard	
Soldermask	IPC-SM840		green, photosensitive	Standard lacquer in the rigid	
				areas	
Flexible solder	JIS C 5012/		green	Partially in the flex area or	
mask	IPC-SM840			over the entire area of the	
				flex side	
Coverlay	IPC-4203	1/2	Polyimide coverlay film,	Optional in place of flex	
	JPCA-DG04		acrylic or epoxy glue	solder mask (surcharge)	

Standard Stackups

The standard stackups you will find under www.we-online.com/flex.



<u>Combination with microvia technique and buried via technique is possible:</u> See WE HDI Microvia Design Guide.

- <u>Flex side</u>: Microvias through dielectric 100μm thick. Always specify microvia-in-solder pad with copperfilling (filling ratio ≥70%)!
- Rigid side: Microvias can also be designed with 60µm dielectric by consultation.
- <u>Buried vias</u> after consultation by modification of the stackup (additional costs due to additional multilayer process).

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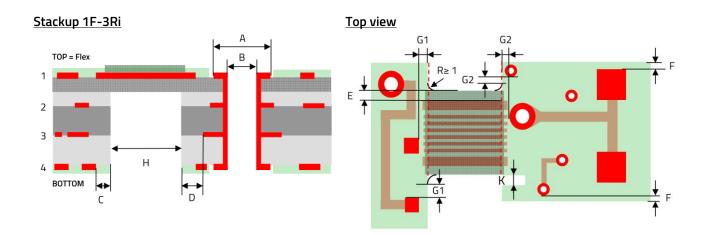


Standard design

- 1. Flexible layer out of Polyimide 50µm adhesive less, PCB total thickness 0.8mm to 1.55mm
- 2. Copper layer thickness inner layers 18µm, outer layers 12µm + plated copper
- 3. Low-Flow Prepreg between flexible and rigid material
- 4. Flexible soldermask green on flex side, not flex side or optional all rigid areas with standard green solder resist epoxy
- 5. Standard PTH (Plated Through Holes)
- 6. Smallest milling diameter 1.6 mm
- 7. Solderable surface ENIG
- 8. Packaged in ESD shrink wrap

Design RulesRIGID**.flex** 1F-xRi





Symbol	Description	Technical Standard	Advanced requirements
	Line widths and spacings	see WE BASIC Design Rules!	
А	Minimum via pad diameter →For all Pad-connections Teardrops are recommended!	see WE BASIC Design Rules!	
В	Final diameter of PTH	see WE BASIC Design Rules!	
С	Spacing, Cu – outer layer to flex-rigid transition (bottom)	≥300µm	
D	Spacing, Cu – inner layer to flex-rigid transition	≥800µm	
E	Distance of conductor to the flexible contour	≥300µm	
F	Spacing, exposed Cu – outside of flex-rigid transition	≥300µm	
G1	Flexible lacquer: Spacing, exposed Cu to flex-rigid transition (top)	≥800µm	≥400µm
G2	Flexible lacquer: Spacing, drillpad to flex-rigid transition (top)	≥1000µm	≥800µm
G1 + G2	Coverlay: Spacing to flex-rigid transition, exposed Cu (top) and drillpad	≥1500µm	≥1000µm
G1 + G2	Coverlay with UL marking : Spacing to flex-rigid transition for exposed Cu (top) and for drillpad	≥2000µm	≥1500µm
Н	Length of the flex area	≥5mm	≥2.5mm
К	Minimum recess width directly at the flex area	1.6mm	1.0mm
"K"	Outline manufacturing of flex area: No scoring permitted!		
"ZIF"	ZIF contacts thickness tolerance (material of stiffener)	± 0.05mm (FR4)	± 0.03mm (PI) special stackup
-	Combination with microvia and buried via technique is possible	see HDI Microvia	Design Guide!

Further specifications available on request, please contact us: flex@we-online.com